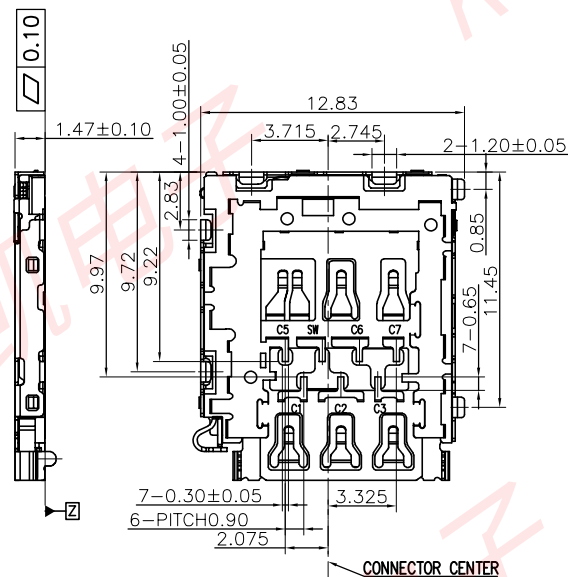
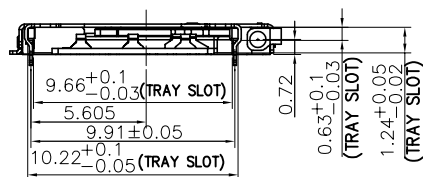
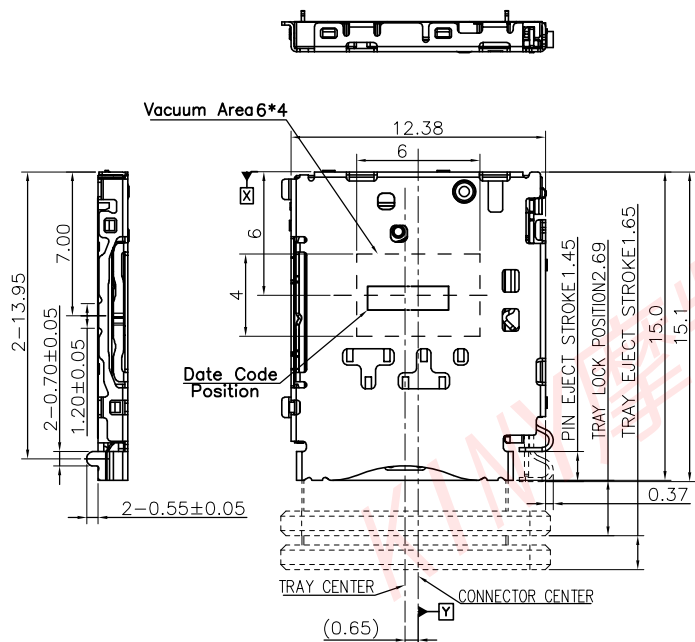
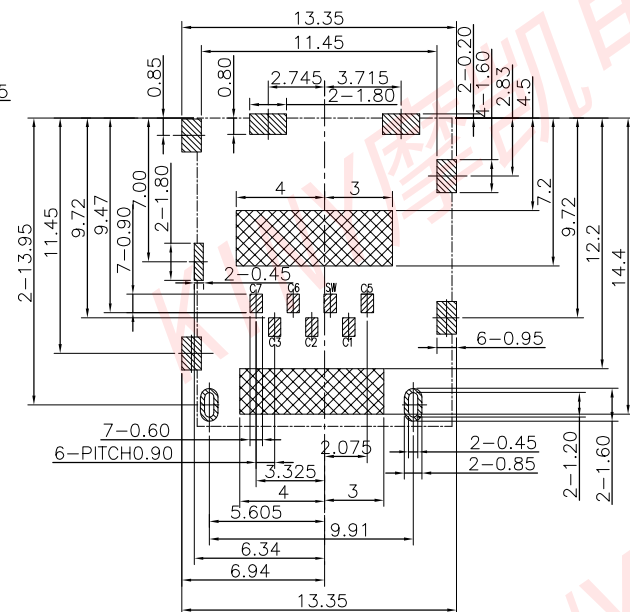


* 所有原材料, 生产制程, 电镀必须符合HF要求



COMPOSITION OF DETECTION

CARD DETECT(SW)
C5 SW
CARD DETECTION/SWITCH
CARD INSTALLATION: ON
NON CARD: OFF



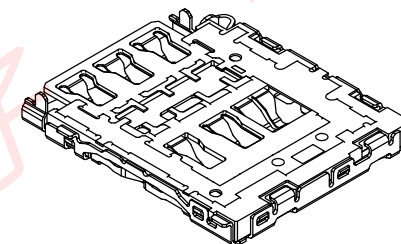
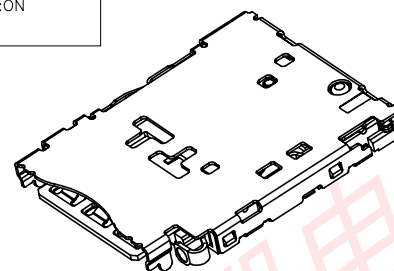
RECOMMEND P.C.B LAYOUT (General tolerance ±0.05)

/// PAD AREA
--- KEEP OUT AREA
--- NO COPPER AREA
(NO Trace&Via&GND)
--- GND PATTERN ONLY

- NOTE:
1. Material:
 - 1-1 Housing: High Temperature Thermoplastic, (LCP) Color Black UL 94V-0
 - 1-2 Contact: Phosphor Bronze (C5210)
 - 1-3 Cover: Stainless steel
 2. Plating:
 - 2-1 Contact terminal:
 - Contact area: Gold 1u" Min.
 - Solder area: Gold 0.8u" Min.
 - Underplating: Ni overall 50u" Min.
 - 2-2 Cover:
 - Underplating: Ni overall 30u" Min.
 - Solder area: Gold 0.8u" Min.
 3. Specification:
 - 3-1. Current Rating: 0.5A max.
 - 3-2. Contact Resistance: 50 mOhms max
 - 3-3. Insulation Resistance: 1000 MOhms min./500VDC
 - 3-4. Dielectric Withstanding Voltage: 500 V AC/1minute
 - 3-5. Operating Temperature: -25°C to +85°C
 - 3-6. Mating Cycles: 5000 Insertions
 4. Product Compliant to RoHS Directive 2002/95/EC and ELV 2000/53/EC
 5. Part Must Comply Taisol HF WD-3-1-091 Specification.
 6. Recommending A Metal More Than 0.15mm Thick.
Please Confirm Solderability, If Use A Metal Mask Less Than 0.15mm Thick.

SIM Card Pin Assignments

NANO SIM CARD	
C1	Vcc
C2	RST
C3	CLK
C5	GND
SW	CD/SW
C6	Vpp
C7	DATA



KINY

东莞市摩凯电子有限公司

DIMENSIONS INIT: mm
UNLESS OTHERWISE SPECIFIABLE
DIMENSION TOLERANCE
X.X: ± 0.35
X.XX: ± 0.20
X.XXX: ± 0.10
ANGULAR: ± 2'

PRODUCT NAME : NANO SIM H1.50 CARD CONN(DIP)	DRAWING: Janyz	DATE: 2018.11.19
PRODUCT NO. : NS150-D1131-04	CHECK: Alex	DATE: 2018.11.19
DRAWING NO. : D-NS150-D1131-04	APPROVED: Alex	DATE: 2018.11.19
SCALE: 1:1	DWG ID: C D	REV.: C
		PAGE: 1 OF 1

C	ECN20181119001	修改参数	janyz	2018.11.19
A	----	NEW RELEASE	ping	2017.06.15
REVISION NO.	ECR NO.	DESCRIPTION	MARK	DATE